

### Is Now Part of



# ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at <a href="https://www.onsemi.com">www.onsemi.com</a>

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo



August 2016

# MCT6, MCT61, MCT62 8-Pin Dual Channel Phototransistor Optocouplers

### **Features**

- · Two Isolated Channels Per Package
- · Safety and Regulatory Approvals:
  - UL1577, 5,000 VAC  $_{RMS}$  for 1 Minute
  - DIN-EN/IEC60747-5-5, 890 V Peak Working Insulation Voltage

# **Applications**

- AC line/digital logic isolate high voltage transients
- Digital logic/digital logic eliminate spurious grounds
- · Digital logic/AC triac control isolate high voltage
- transients
- Twisted pair line receiver eliminate ground loop
- feedthrough
- Telephone/telegraph line receiver isolate high
- voltage transients
- · High frequency power supply feedback control -
- · maintain floating grounds and transients
- Relay contact monitor isolate floating grounds and
- transients
- Power supply monitor isolate transients

# Description

The general purpose optocouplers, MCT6, MCT61, and MCT62, have two isolated channels in a standard plastic 8-pin dual-in-line (DIP) package for density applications. Each channel consists of a gallium arsenide infrared emitting diode driving a NPN silicon planar phototransistor. For four channel applications, two packages fit into a standard 16-pin DIP socket.

# Functional Schematic

# ANODE 1 CATHODE 2 7 COLLECTOR 6 COLLECTOR ANODE 4 5 EMITTER

Figure 1. Schematic

# **Package Outlines**

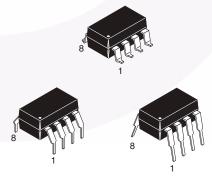


Figure 2. Package Outlines

# **Safety and Insulation Ratings**

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

| Parameter                                  | Characteristics        |           |
|--|------------------------|-----------|
| Installation Classifications per DIN VDE   | < 150 V <sub>RMS</sub> | I–IV      |
| 0110/1.89 Table 1, For Rated Mains Voltage | < 300 V <sub>RMS</sub> | I–IV      |
| Climatic Classification                    |                        | 55/115/21 |
| Pollution Degree (DIN VDE 0110/1.89)       |                        | 2         |
| Comparative Tracking Index                 |                        | 175       |

| Symbol                | Parameter  | Value             | Unit              |
|-----------------------|--|-------------------|-------------------|
| V <sub>PR</sub>       | Input-to-Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$ , Type and Sample Test with $t_m = 10 \text{ s}$ , Partial Discharge < 5 pC | 1424              | V <sub>peak</sub> |
| V PR                  | Input-to-Output Test Voltage, Method B, $V_{IORM} \times 1.875 = V_{PR}$ , 100% Production Test with $t_m = 1$ s, Partial Discharge < 5 pC         | 1668              | V <sub>peak</sub> |
| V <sub>IORM</sub>     | Maximum Working Insulation Voltage   | 890               | V <sub>peak</sub> |
| V <sub>IOTM</sub>     | Highest Allowable Over-Voltage   | 8000              | V <sub>peak</sub> |
|                       | External Creepage  | ≥ 7               | mm                |
|                       | External Clearance   | ≥ 7               | mm                |
| DTI                   | Distance Through Insulation (Insulation Thickness)   | ≥ 0.4             | mm                |
| T <sub>S</sub>        | Case Temperature <sup>(1)</sup>  | 175               | °C                |
| I <sub>S,INPUT</sub>  | Input Current <sup>(1)</sup>   | 60                | mA                |
| P <sub>S,OUTPUT</sub> | Output Power <sup>(1)</sup>  | 150               | mW                |
| R <sub>IO</sub>       | Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V <sup>(1)</sup>   | > 10 <sup>9</sup> | Ω                 |

### Note:

1. Safety limit values – maximum values allowed in the event of a failure.

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A = 25^{\circ}C$  unless otherwise specified.

| Symbol                   | Parameter  | Value                   | Unit  |
|--------------------------|--|-------------------------|-------|
| T <sub>STG</sub>         | Storage Temperature                                    | -55 to +150             | °C    |
| T <sub>OPR</sub>         | Operating Temperature                                  | -55 to +100             | °C    |
| T <sub>J</sub>           | Junction Temperature                                   | -55 to +125             | °C    |
| T <sub>SOL</sub>         | Lead Solder Temperature                                | 260 for 10 sec-<br>onds | °C    |
| D                        | Total Device Power Dissipation @ T <sub>A</sub> = 25°C | 400                     | mW    |
| $P_{D}$                  | Derate Above 25°C                                      | 5.33                    | mW/°C |
| EMITTER (Eac             | h channel)   |                         |       |
| IF                       | DC / Average Forward Input Current                     | 60                      | mA    |
| I <sub>F</sub> (pk)      | Forward Current - Peak (PW = 1µs, 300pps)              | 3                       | Α     |
| V <sub>R</sub>           | Reverse Input Voltage                                  | 3                       | V     |
| В                        | Total Power Dissipation @ T <sub>A</sub> = 25°C        | 100                     | mW    |
| P <sub>D(EMITTER)</sub>  | Derate Above 25°C                                      | 1.3                     | mW/°C |
| DETECTOR                 |  |                         |       |
| I <sub>C</sub>           | Continuous Collector Current                           | 30                      | mA    |
| D                        | Total Power Dissipation @ T <sub>A</sub> = 25°C        | 150                     | mW    |
| P <sub>D(DETECTOR)</sub> | Derate Above 25°C                                      | 2.0                     | mW/°C |

# **Electrical Characteristics**

 $T_A = 25$ °C unless otherwise specified.

# **Individual Component Characteristics**

| Symbol            | Parameter                              | Test Conditions                             | Min. | Тур.  | Max. | Unit |
|-------------------|--|---|------|-------|------|------|
| <b>EMITTER</b>    |  |   | •    |       |      |      |
| V <sub>F</sub>    | Input Forward Voltage                  | I <sub>F</sub> = 20 mA                      |      | 1.2   | 1.5  | V    |
| V <sub>R</sub>    | Reverse Voltage                        | I <sub>R</sub> = 10 μA                      | 3    | 25    |      | V    |
| I <sub>R</sub>    | Reverse Leakage Current                | V <sub>R</sub> = 5 V                        |      | 0.001 | 10   | μΑ   |
| CJ                | Junction Capacitance                   | V <sub>F</sub> = 0 V, f = 1 MHz             |      | 50    |      | pF   |
| DETECTO           | DR .                                   |   |      |       |      |      |
| BV <sub>CEO</sub> | Collector-to-Emitter Breakdown Voltage | I <sub>C</sub> = 1.0 mA, I <sub>F</sub> = 0 | 30   | 85    |      | V    |
| BV <sub>ECO</sub> | Emitter-to-Collector Breakdown Voltage | I <sub>E</sub> = 100 μA, I <sub>F</sub> = 0 | 6    | 13    |      | V    |
| I <sub>CEO</sub>  | Collector-to-Emitter Dark Current      | V <sub>CE</sub> = 10 V, I <sub>F</sub> = 0  |      | 5     | 100  | nA   |
| C <sub>CE</sub>   | Capacitance                            | V <sub>CE</sub> = 0 V, f = 1 MHz            |      | 8     |      | pF   |

### **Transfer Characteristics**

| Symbol               | Parameter                                    | Device | Test Conditions                                | Min. | Тур. | Max. | Unit |
|----------------------|--|--------|--|------|------|------|------|
| DC CHARACTERISTICS   |  |        |  |      |      |      |      |
|                      |  |        | I <sub>F</sub> = 10 mA, V <sub>CE</sub> = 10 V | 20   |      |      |      |
| CTR                  | CTR Current Transfer Ratio, Collector-       | MCT61  | I <sub>F</sub> = 5 mA, V <sub>CF</sub> = 5 V   | 50   |      |      | %    |
|                      | to-Emitter                                   |        | IF - 5 IIIA, VCE - 5 V                         | 100  |      |      |      |
| VCE <sub>(SAT)</sub> | Saturation Voltage, Collector-to-<br>Emitter | ALL    | I <sub>F</sub> = 16 mA, I <sub>C</sub> = 2 mA  |      | 0.15 | 0.4  | V    |

### **AC CHARACTERISTICS**

| Symbol           | Parameter     | Test Conditions  | Min. | Тур. | Max. | Unit |  |
|------------------|---------------|--|------|------|------|------|--|
| Non-Satu         | Non-Saturated |  |      |      |      |      |  |
| T <sub>ON</sub>  | Turn-On Time  |  |      | 3.0  |      | μs   |  |
| T <sub>OFF</sub> | Turn-Off Time | $R_L$ = 100 Ω, $I_C$ = 2 mA, $V_{CC}$ = 10 V   |      | 3.0  |      | μs   |  |
| $T_{R}$          | Rise Time     |  |      | 2.4  |      | μs   |  |
| T <sub>F</sub>   | Fall Time     |  |      | 2.4  |      | μs   |  |
| Saturated        |               |  |      |      |      |      |  |
| T <sub>ON</sub>  | Turn-On Time  | $I_F$ = 16 mA, $R_I$ = 1.9 kΩ, $V_{CF}$ = 5 V  |      | 2.4  |      | μs   |  |
| T <sub>OFF</sub> | Turn-Off Time | ]   - 10 111A, 1\(\mathbb{L} - 1.9 \text{ K}\(\mathbb{Z}\), \(\mathbb{C}\)E = 3 \(\mathbb{V}\) |      | 25.0 |      | μs   |  |

### **Isolation Characteristics**

| Symbol           | Parameter                      | Test Conditions                        | Min.             | Тур. | Max. | Unit               |
|------------------|--------------------------------|--|------------------|------|------|--------------------|
| V <sub>ISO</sub> | Input-Output Isolation Voltage | I <sub>I-O</sub> ≤ 10 μA, t = 1 Minute | 5,000            |      |      | VAC <sub>RMS</sub> |
| C <sub>ISO</sub> | Isolation Capacitance          | f = 1 MHz                              |                  | 0.5  |      | pF                 |
| R <sub>ISO</sub> | Isolation Resistance           | V <sub>I-O</sub> = 500 VDC             | 10 <sup>11</sup> |      |      | Ω                  |

# **Typical Performance Curves**

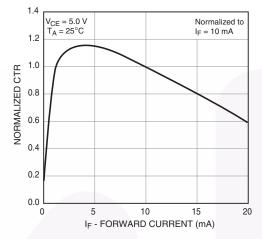


Fig. 3 Normalized CTR vs. Forward Current

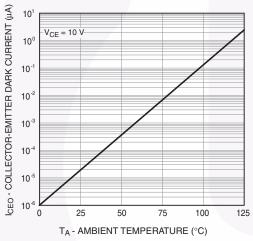


Fig. 5 Dark Current vs. Ambient Temperature

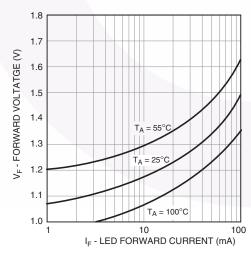


Fig. 7 LED Forward Voltage vs. Forward Current

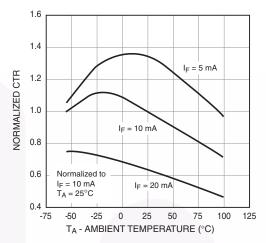


Fig. 4 Normalized CTR vs. Ambient Temperature

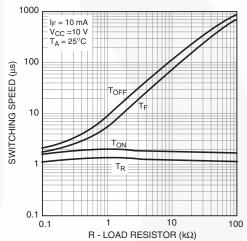


Fig. 6 Switching Speed vs. Load Resistor

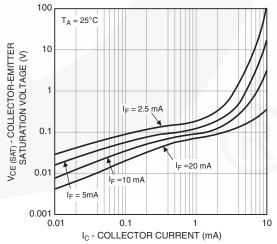


Fig. 8 Collector-Emitter Saturation Voltage vs. Collector Current

# **Switching Time Test Circuit and Waveforms**

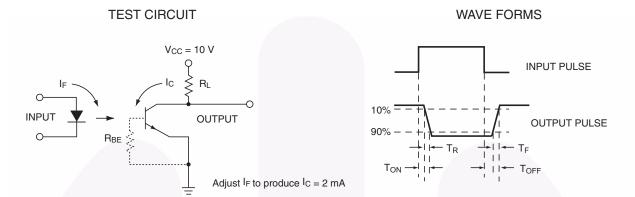
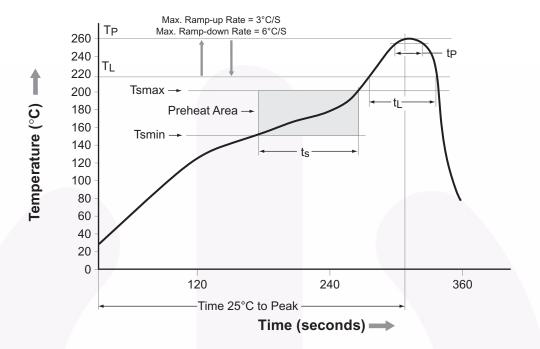


Figure 9. Switching Time Test Circuit and Waveforms

# **Reflow Profile**



| Profile Feature   | Pb-Free Assembly Profile |  |
|---|--------------------------|--|
| Temperature Min. (Tsmin)                                  | 150°C                    |  |
| Temperature Max. (Tsmax)                                  | 200°C                    |  |
| Time (t <sub>S</sub> ) from (Tsmin to Tsmax)              | 60-120 seconds           |  |
| Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )          | 3°C/second max.          |  |
| Liquidous Temperature (T <sub>L</sub> )                   | 217°C                    |  |
| Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> ) | 60-150 seconds           |  |
| Peak Body Package Temperature                             | 260°C +0°C / -5°C        |  |
| Time (t <sub>P</sub> ) within 5°C of 260°C                | 30 seconds               |  |
| Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )        | 6°C/second max.          |  |
| Time 25°C to Peak Temperature                             | 8 minutes max.           |  |

# **Ordering Information**

| Part Number | Package  | Packing Method                       |
|-------------|--|--------------------------------------|
| MCT6        | DIP 8-Pin  | Tube (50 units per tube)             |
| MCT6S       | SMT 8-Pin (Lead Bend) Tube (50 units per tube)     |                                      |
| MCT6SD      | SMT 8-Pin  | Tape and Reel (1,000 units per reel) |
| MCT6300     | DIN EN/IEC 60747-5-5 Option                        | Tube (50 units per tube)             |
| MCT63S      | SMT 8-Pin (Lead Bend); DIN EN/IEC 60747-5-5 Option | Tube (50 units per tube)             |
| MCT63SD     | SMT 8-Pin; DIN EN/IEC 60747-5-5 Option             | Tape and Reel (1,000 units per reel) |
| MCT6300W    | 0.4" Lead Spacing; DIN EN/IEC 60747-5-5 Option     | Tube (50 units per tube)             |

### Note

1. The product orderable part number system listed in this table also applies to the MCT61 and MCT62.

# **Marking Information**

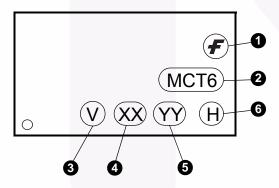
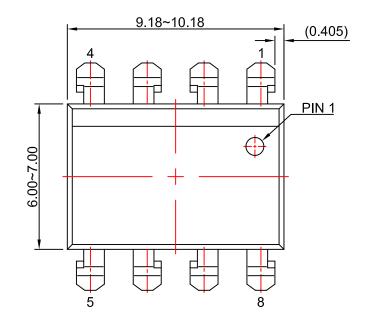
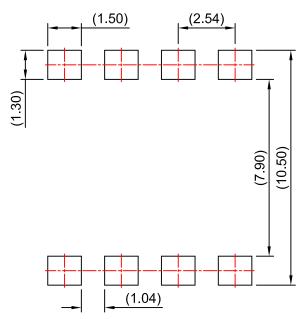


Figure 10. Top Mark

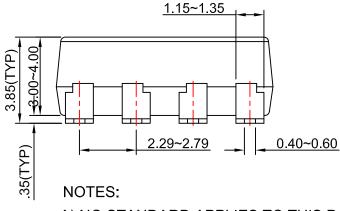
# **Table 1. Top Mark Definitions**

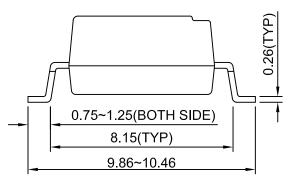
| 1 | Fairchild Logo  |
|---|---|
| 2 | Device Number   |
| 3 | DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option) |
| 4 | Two-Digit Year Code, e.g., "16"   |
| 5 | Digit Work Week, Ranging from "01" to "53"                                      |
| 6 | Assembly Package Code   |





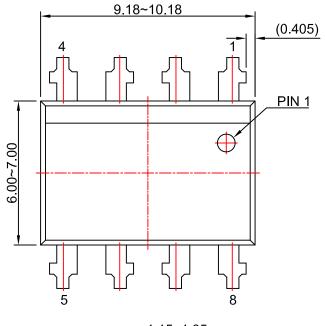
# LAND PATTERN RECOMMENDATION

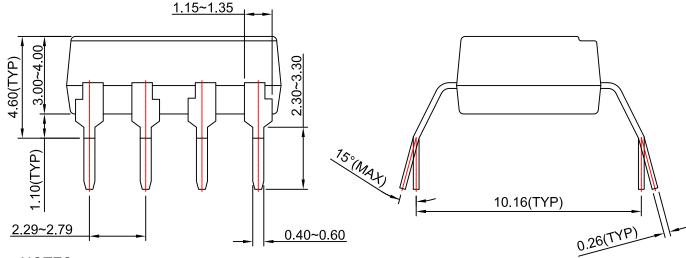




- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVSION: MKT-N08Krev2.



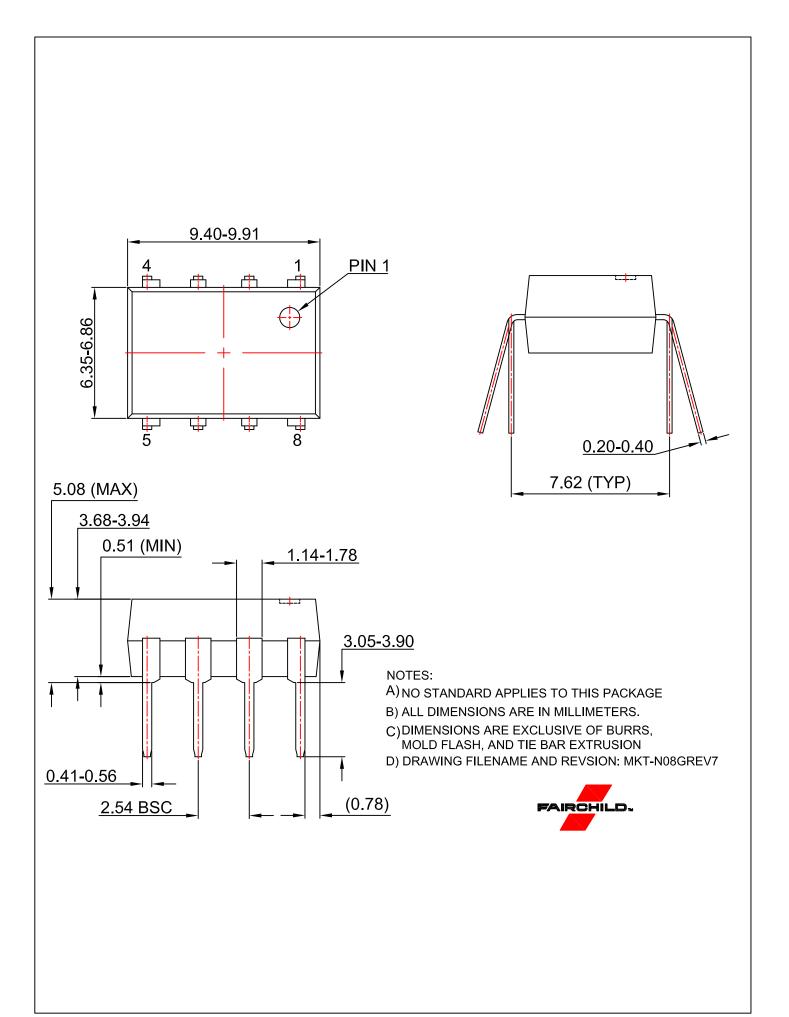




# NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVSION: MKT-N08Jrev2.









### TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

 $\begin{array}{lll} \mathsf{AccuPower^{\mathsf{TM}}} & \mathsf{F-PFS^{\mathsf{TM}}} \\ \mathsf{AttitudeEngine^{\mathsf{TM}}} & \mathsf{FRFET}^{\texttt{®}} \end{array}$ 

Awinda<sup>®</sup> Global Power Resource SM

AX-CAP®\* GreenBridge™
BitSiC™ Green FPS™
Build it Now™ Green FPS™ e-Series™

Current Transfer Logic™ Making Small Speakers Sound Louder

DEUXPEED® and Better™

Dual Cool™ MegaBuck™

EcoSPARK® MICROCOUPLER™

EfficientMax™ MicroFET™

EfficientMax™ MicroFET™
ESBC™ MicroPak™
MicroPak™
MicroPak2™
Fairchild® MillerDrive™
MotionMax™
Fairchild Semiconductor®

Farchild Semiconductor

FACT Quiet Series™
FACT®

FastvCore™
FETBench™
FPS™

MotionGrid®
MTI®
MTX®
MVN®
FETBench™
MVN®
FPS™

OptoHiT™
OPTOLOGIC®

OPTOPLANAR®

Power Supply WebDesigner™ PowerTrench®

PowerXS™

Programmable Active Droop™ OFFT®

QS™ Quiet Series™ RapidConfigure™

T TM

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™
Sync-Lock™

SYSTEM GENERAL®'
TinyBoost®
TinyBuck®
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyPWM™
TranSiC™
TriFault Detect™
TRUECURRENT®\*\*
uSerDes™

SerDes"
UHC<sup>®</sup>
Ultra FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XS™
XS™
XS™

仙童®

\* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT <a href="http://www.fairchildsemi.com">http://www.fairchildsemi.com</a>, FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

### AUTHORIZED USE

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application – including life critical medical equipment – where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

### **ANTI-COUNTERFEITING POLICY**

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Terms of Use

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

### PRODUCT STATUS DEFINITIONS

### **Definition of Terms**

| Deminition of Terms      |                       |   |
|--------------------------|-----------------------|---|
| Datasheet Identification |                       | Definition  |
| Advance Information      | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.   |
| Preliminary              | First Production      | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| No Identification Needed | Full Production       | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.   |
| Obsolete                 | Not In Production     | Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.  |

Rev. 177

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Fairchild Semiconductor:

MCT6S MCT6W MCT6SD MCT6